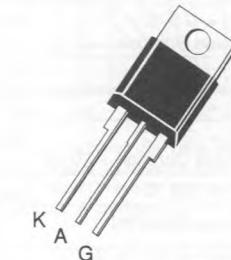


## THYRISTORS

- GLASS PASSIVATED CHIP
- POSSIBILITY OF MOUNTING ON PRINTED CIRCUIT
- AVAILABLE IN NON-INSULATED VERSION -> TYN SERIES OR IN INSULATED VERSION -> TXN SERIES (INSULATING VOLTAGE 2500 VRMS)
- UL RECOGNIZED FOR TXN SERIES (E81734)



**TO 220 AB**  
(Plastic)

### DESCRIPTION

SCR's designed for motor control, heating controls, power supplies...

### ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
$I_{T(RMS)}$	RMS on-state Current (1)	4	A
$I_{T(AV)}$	Mean on-state Current (1)	2.5	A
$I_{TSM}$	Non Repetitive Surge Peak on-state Current ( $T_j$ initial = 25 °C) (2)	73	A
		70	
$I^2t$	$I^2t$ Value for Fusing	24.5	$A^2s$
$dI/dt$	Critical Rate of Rise of on-state Current (3)	50	$A/\mu s$
$T_{sig}$ $T_j$	Storage and Operating Junction Temperature Range	- 40 to 110	°C
		- 40 to 110	°C

Symbol	Parameter	TXN/TYN							Unit
		054	104	204	404	604	804	1004	
$V_{DRM}$ $V_{RRM}$	Repetitive Peak off-state Voltage (4)	50	100	200	400	600	800	1000	V

(1) Single phase circuit, 180° conduction angle.

(2) Half sine wave.

(3)  $I_G = 150 \text{ mA}$     $dI/dt = 1 \text{ A}/\mu \text{s}$ .

(4)  $T_j = 110 \text{ }^\circ\text{C}$ .

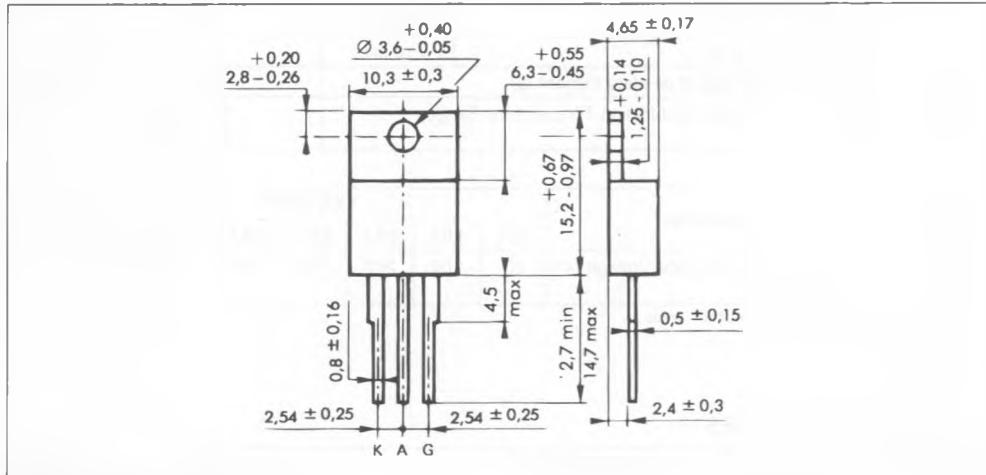
### THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	Junction-case for D.C.	5	$^\circ\text{C/W}$
$R_{th(j-a)}$	Junction-ambient	60	$^\circ\text{C/W}$

**GATE CHARACTERISTICS** (maximum values) $P_{GM} = 20 \text{ W}$  ( $t_p = 20 \mu\text{s}$ ) $I_{FGM} = 2 \text{ A}$  ( $t_p = 20 \mu\text{s}$ ) $V_{RGM} = 5 \text{ V}$  $P_G(\text{AV}) = 0.5 \text{ W}$  $V_{FGM} = 15 \text{ V}$  ( $t_p = 20 \mu\text{s}$ )**ELECTRICAL CHARACTERISTICS**

Symbol	Test Conditions		Min.	Typ.	Max.	Unit
$I_{GT}$	$T_j = 25^\circ\text{C}$ Pulse Duration > 20 $\mu\text{s}$	$V_D = 12 \text{ V}$	$R_L = 33 \Omega$		15	mA
$V_{GT}$	$T_j = 25^\circ\text{C}$ Pulse Duration > 20 $\mu\text{s}$	$V_D = 12 \text{ V}$	$R_L = 33 \Omega$		1.5	V
$V_{GD}$	$T_j = 110^\circ\text{C}$	$V_D = V_{DRM}$	$R_L = 3.3 \text{ k}\Omega$	0.2		V
$I_H$	$T_j = 25^\circ\text{C}$	$I_T = 100 \text{ mA}$	Gate Open		30	mA
$I_L$	$T_j = 25^\circ\text{C}$ Pulse Duration > 20 $\mu\text{s}$	$V_D = 12 \text{ V}$	$I_G = 30 \text{ mA}$	50		mA
$V_{TM}$	$T_j = 25^\circ\text{C}$	$I_{TM} = 8 \text{ A}$	$t_p = 10 \text{ ms}$		1.8	V
$I_{DRM}$	$V_{DRM}$ Specified		$T_j = 25^\circ\text{C}$		0.01	mA
			$T_j = 110^\circ\text{C}$		1	
$I_{RRM}$	$V_{RRM}$ Specified		$T_j = 25^\circ\text{C}$		0.01	mA
			$T_j = 110^\circ\text{C}$		1	
$t_{g1}$	$T_j = 25^\circ\text{C}$ $I_G = 40 \text{ mA}$	$V_D = V_{DRM}$ $dI_G/dt = 0.45 \text{ A}/\mu\text{s}$	$I_T = 8 \text{ A}$	2		$\mu\text{s}$
$t_q$	$T_j = 110^\circ\text{C}$ $V_D = 67 \% V_{DRM}$ Gate Open	$I_T = 8 \text{ A}$ $dI/dt = 30 \text{ A}/\mu\text{s}$	$V_R = 25 \text{ V}$ $dv/dt = 50 \text{ V}/\mu\text{s}$	70		$\mu\text{s}$
$dv/dt^*$	$T_j = 110^\circ\text{C}$ Linear Slope up to $V_D = 67 \% V_{DRM}$	Gate Open		200		$\text{V}/\mu\text{s}$

\* For higher guaranteed values, please consult us.

**PACKAGE MECHANICAL DATA : TO 220 AB Plastic**

Cooling method : by conduction (method C)

Marking : type number

Weight : 2 g

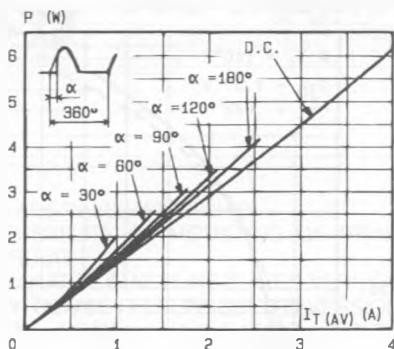


Fig.1 - Maximum mean power dissipation versus mean on-state current.

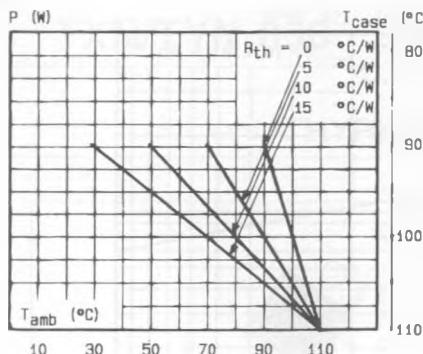


Fig.2 - Correlation between maximum mean power dissipation and maximum allowable temperatures ( $T_{amb}$  and  $T_{case}$ ) for different thermal resistances heatsink + contact.

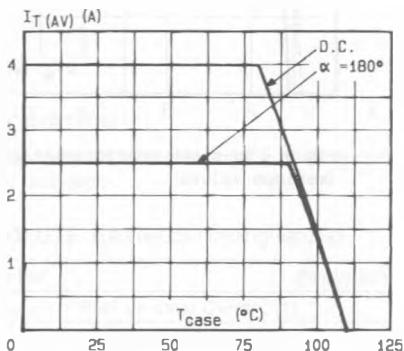


Fig.3 - Mean on-state current versus case temperature.

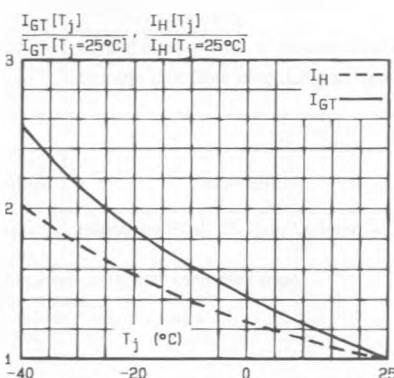


Fig.5 - Relative variation of gate trigger current and holding current versus junction temperature.

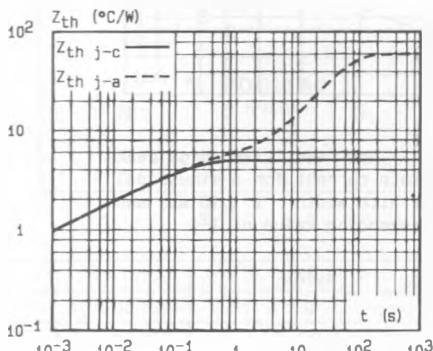


Fig.4 - Thermal transient impedance junction to case and junction to ambient versus pulse duration.

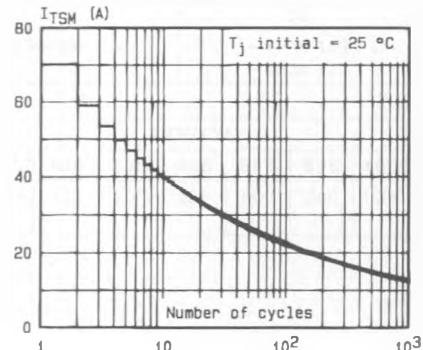


Fig.6 - Non repetitive surge peak on-state current versus number of cycles.

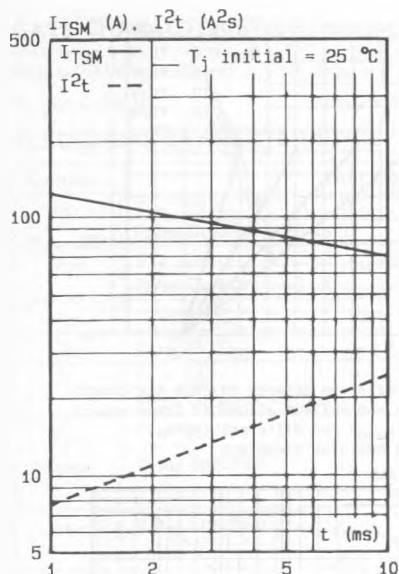


Fig.7 - Non repetitive surge peak on-state current for a sinusoidal pulse with width :  $t \leq 10$  ms, and corresponding value of  $I^2t$ .

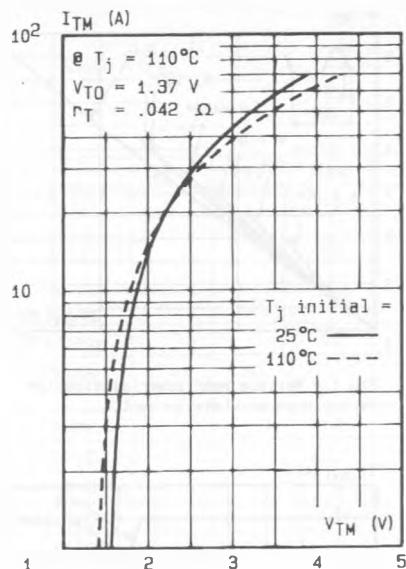


Fig.8 - On-state characteristics (maximum values).